

# HD74ALVC2G125

## Dual Bus Buffer with 3-state Output

REJ03D0171-0200Z (Previous ADE-205-621A (Z)) Rev.2.00 Dec.18.2003

### **Description**

The HD74ALVC2G125 has dual bus buffer with 3-state output in an 8 pin package. Output is disabled when the associated output enable  $(\overline{OE})$  input is high. To ensure the high impedance state during power up or power down,  $\overline{OE}$  should be connected to  $V_{CC}$  through a pull-up resistor; the minimum value of the resistor is determined by the current sinking capability of the driver. Low voltage and high-speed operation is suitable for the battery powered products (e.g., notebook computers), and the low power consumption extends the battery life.

#### **Features**

- The basic gate function is lined up as Renesas uni logic series.
- Supplied on emboss taping for high-speed automatic mounting.
- Supply voltage range: 1.2 to 3.6 V
   Operating temperature range: -40 to +85°C
- All inputs  $V_{IH}$  (Max.) = 3.6 V (@ $V_{CC}$  = 0 V to 3.6 V)

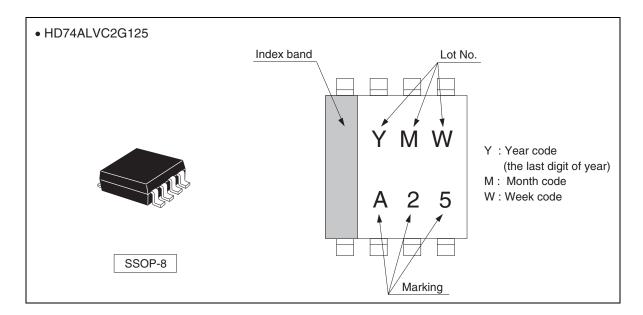
All outputs  $V_0$  (Max.) = 3.6 V (@ $V_{CC}$  = 0 V)

$$\begin{array}{ll} \bullet & \text{Output current} & \pm 2 \text{ mA } (@V_{CC} = 1.2 \text{ V}) \\ & \pm 4 \text{ mA } (@V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}) \\ & \pm 6 \text{ mA } (@V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}) \\ & \pm 18 \text{ mA } (@V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}) \\ & \pm 24 \text{ mA } (@V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}) \end{array}$$

• Ordering Information

Part Name	Package Type	Package Code	Package Abbreviation	Taping Abbreviation (Quantity)
HD74ALVC2G125USE	SSOP-8 pin	TTP-8DBV	US	E (3,000 pcs/reel)

### **Outline and Article Indication**



### **Function Table**

### Inputs

ŌĒ	A	Output Y
L	Н	Н
L	L	L
Н	X	Z

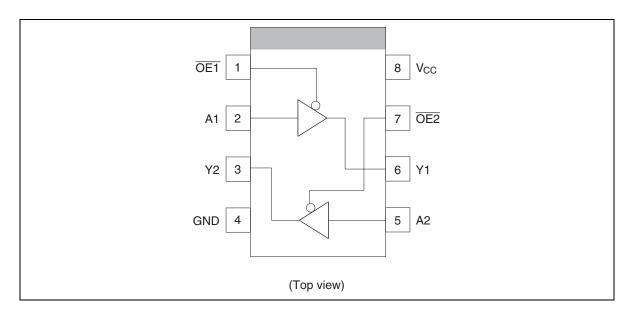
H: High level

L: Low level

X: Immaterial

Z: High impedance

### **Pin Arrangement**



### **Absolute Maximum Ratings**

Item	Symbol	Ratings	Unit	Conditions
Supply voltage range	$V_{CC}$	-0.5 to 4.6	V	
Input voltage range *1	Vı	-0.5 to 4.6	V	
Output voltage range *1, 2	Vo	-0.5 to V <sub>CC</sub> +0.5	V	Output : H or L or Z
		-0.5 to 4.6	_	V <sub>CC</sub> : OFF
Input clamp current	I <sub>IK</sub>	<b>-50</b>	mA	V <sub>I</sub> < 0
Output clamp current	I <sub>OK</sub>	±50	mA	$V_O < 0$ or $V_O > V_{CC}$
Continuous output current	lo	±50	mA	$V_{O} = 0$ to $V_{CC}$
Continuous current through V <sub>CC</sub> or GND	I <sub>CC</sub> or I <sub>GND</sub>	±100	mA	
Maximum power dissipation at Ta = 25°C (in still air) <sup>*3</sup>	P <sub>T</sub>	200	mW	
Storage temperature	Tstg	-65 to 150	°C	

Notes: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

- 1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- 2. This value is limited to 4.6 V maximum.
- 3. The maximum package power dissipation was calculated using a junction temperature of 150°C.

### HD74ALVC2G125

### **Recommended Operating Conditions**

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage range	V <sub>CC</sub>	1.2	3.6	V	
Input voltage range	VI	0	3.6	V	
Output voltage range	Vo	0	Vcc	V	
Output current	I <sub>OH</sub>	_	-2	mA	V <sub>CC</sub> = 1.2 V
		_	-4		V <sub>CC</sub> = 1.4 V
		_	-6		V <sub>CC</sub> = 1.65 V
		_	-18		V <sub>CC</sub> = 2.3 V
		_	-24		V <sub>CC</sub> = 3.0 V
	I <sub>OL</sub>	_	2		V <sub>CC</sub> = 1.2 V
		_	4		V <sub>CC</sub> = 1.4 V
			6		V <sub>CC</sub> = 1.65 V
			18		V <sub>CC</sub> = 2.3 V
		_	24		V <sub>CC</sub> = 3.0 V
Input transition rise or fall rate	Δt / Δν	0	20	ns / V	V <sub>CC</sub> = 1.2 to 2.7 V
		0	10		V <sub>CC</sub> = 3.3±0.3 V
Operating free-air temperature	Та	-40	85	°C	

Note: Unused or floating inputs must be held high or low.

### **Electrical Characteristics**

 $(Ta = -40 \text{ to } 85^{\circ}C)$ 

Item	Symbol	V <sub>CC</sub> (V) <sup>*</sup>	Min	Тур	Max	Unit	Test conditions
Input voltage	V <sub>IH</sub>	1.2	V <sub>CC</sub> ×0.75	_	_	V	
		1.4 to 1.6	V <sub>CC</sub> ×0.7	_	_	_	
		1.65 to 1.95	V <sub>CC</sub> ×0.7	_	_	_	
		2.3 to 2.7	1.7	_	_	_	
		3.0 to 3.6	2.0	_	_	_	
	V <sub>IL</sub>	1.2	_	_	V <sub>CC</sub> ×0.25	_	
		1.4 to 1.6	_	_	V <sub>CC</sub> ×0.3	_	
		1.65 to 1.95	_	_	V <sub>CC</sub> ×0.3	_	
		2.3 to 2.7	_	_	0.7	_	
		3.0 to 3.6	_	_	0.8	=	
Output voltage	V <sub>OH</sub>	Min to Max	V <sub>CC</sub> -0.2	_	_	V	$I_{OH} = -100  \mu A$
		1.2	0.9	_	_	_	$I_{OH} = -2 \text{ mA}$
		1.4	1.1	_	_	_	$I_{OH} = -4 \text{ mA}$
		1.65	1.2	_	_	_	$I_{OH} = -6 \text{ mA}$
		2.3	1.7	_	_	_	$I_{OH} = -18 \text{ mA}$
		3.0	2.2	_	_	_	$I_{OH} = -24 \text{ mA}$
	V <sub>OL</sub>	Min to Max	_	_	0.2	_	$I_{OL} = 100 \mu\text{A}$
		1.2	_	_	0.3	_	$I_{OL} = 2 \text{ mA}$
		1.4	_	_	0.3	_	I <sub>OL</sub> = 4 mA
		1.65	_	_	0.3	_	$I_{OL} = 6 \text{ mA}$
		2.3	_	_	0.55	_	I <sub>OL</sub> = 18 mA
		3.0	_	_	0.55	_	I <sub>OL</sub> = 24 mA
Input current	I <sub>IN</sub>	3.6	_	_	±5	μΑ	$V_{IN} = 3.6 \text{ V or GND}$
Off state output current	l <sub>OZ</sub>	3.6	_		±5	μΑ	$V_O = V_{CC}$ or GND
Quiescent supply current	I <sub>CC</sub>	3.6	_	_	10	μΑ	$V_{IN} = V_{CC}$ or GND, $I_O = 0$
Output leakage current	I <sub>OFF</sub>	0	_	_	5	μΑ	V <sub>IN</sub> or V <sub>O</sub> = 0 to 3.6 V
Input capacitance	C <sub>IN</sub>	3.3	_	4.5	_	pF	$V_{IN} = V_{CC}$ or GND

Note: For conditions shown as Min or Max, use the appropriate values under recommended operating conditions.

### **Switching Characteristics**

 $(Ta = -40 \text{ to } 85^{\circ}C)$ 

 $V_{CC} = 1.2 \text{ V}$ 

Item	Symbol	Min	Тур	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Propagation delay time	t <sub>PLH</sub> t <sub>PHL</sub>	_	5.5	_	ns	$C_L = 15 pF$	Α	Υ
Enable time	t <sub>ZH</sub> t <sub>ZL</sub>	_	6.5	_	ns	C <sub>L</sub> = 15 pF	ŌĒ	Υ
Disable time	t <sub>HZ</sub> t <sub>LZ</sub>	_	4.5	_	ns	C <sub>L</sub> = 15 pF	ŌĒ	Υ

 $V_{CC} = 1.5 \pm 0.1 \text{ V}$ 

Item	Symbol	Min	Тур	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Propagation delay time	t <sub>PLH</sub> t <sub>PHL</sub>	2.0	_	7.0	ns	$C_L = 15 pF$	Α	Υ
Enable time	t <sub>ZH</sub> t <sub>ZL</sub>	2.0	_	7.0	ns	C <sub>L</sub> = 15 pF	ŌĒ	Υ
Disable time	t <sub>HZ</sub> t <sub>LZ</sub>	2.0	_	7.0	ns	$C_L = 15 pF$	ŌĒ	Υ

 $V_{CC} = 1.8 \pm 0.15 \text{ V}$ 

Item	Symbol	Min	Тур	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Propagation delay time	t <sub>PLH</sub> t <sub>PHL</sub>	1.5	_	5.0	ns	$C_L = 30 pF$	Α	Υ
Enable time	t <sub>ZH</sub> t <sub>ZL</sub>	1.5	_	5.0	ns	C <sub>L</sub> = 30 pF	ŌĒ	Y
Disable time	t <sub>HZ</sub> t <sub>LZ</sub>	1.5	_	5.0	ns	C <sub>L</sub> = 30 pF	ŌĒ	Y

### **Switching Characteristics** (cont)

 $V_{CC} = 2.5 \pm 0.2 \text{ V}$ 

Item	Symbol	Min	Тур	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Propagation delay time	t <sub>PLH</sub> t <sub>PHL</sub>	1.0	_	4.0	ns	$C_L = 30 pF$	Α	Y
Enable time	t <sub>ZH</sub>	1.0	_	4.0	ns	C <sub>L</sub> = 30 pF	ŌĒ	Y
Disable time	t <sub>HZ</sub> t <sub>LZ</sub>	1.0	_	4.0	ns	$C_L = 30 pF$	ŌĒ	Υ

 $V_{CC} = 3.3 \pm 0.3 \text{ V}$ 

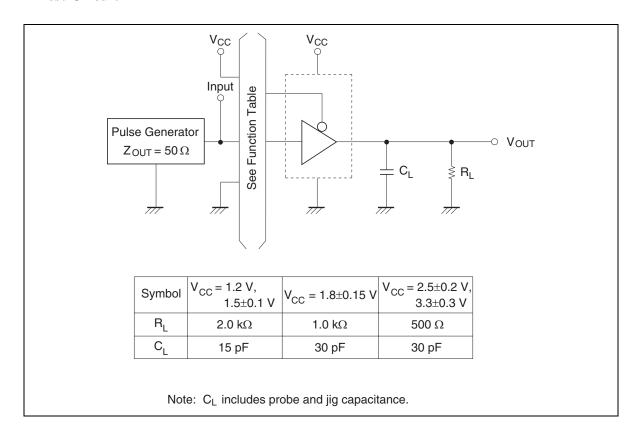
Item	Symbol	Min	Тур	Max	Unit	Test conditions	FROM (Input)	TO (Output)
Propagation delay time	t <sub>PLH</sub> t <sub>PHL</sub>	1.0	_	3.0	ns	$C_L = 30 pF$	Α	Υ
Enable time	t <sub>ZH</sub> t <sub>ZL</sub>	1.0	_	3.0	ns	C <sub>L</sub> = 30 pF	ŌĒ	Υ
Disable time	t <sub>HZ</sub> t <sub>LZ</sub>	1.0	_	3.0	ns	$C_L = 30 pF$	ŌĒ	Υ

### **Operating Characteristics**

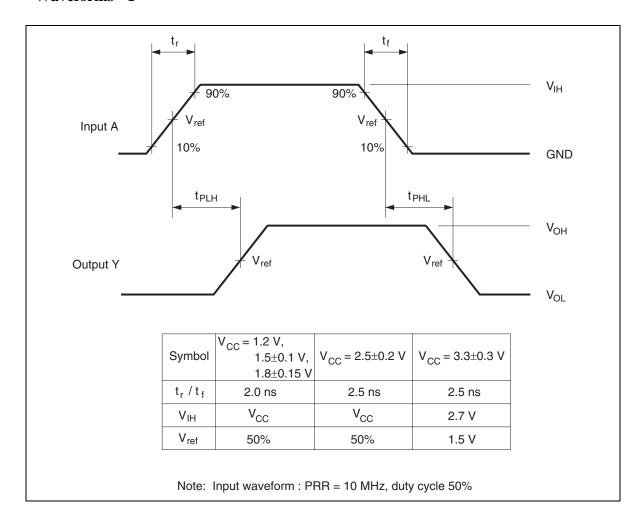
 $(Ta = 25^{\circ}C)$ 

Item	Symbol	V <sub>CC</sub> (V)	Min	Тур	Max	Unit	Test conditions
Power dissipation	$C_{PD}$	1.5	_	10.5		pF	f = 10 MHz
capacitance		1.8	_	10.5		<del>_</del>	
		2.5	_	11.0		<del></del>	
		3.3	_	13.0			

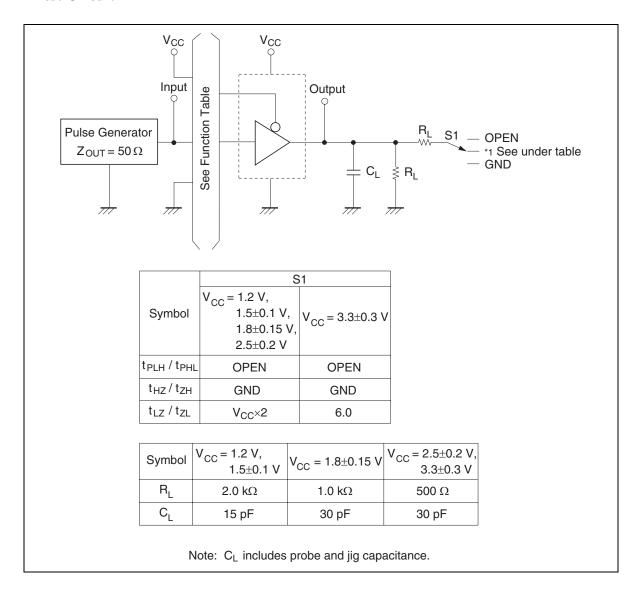
### **Test Circuit - 1**



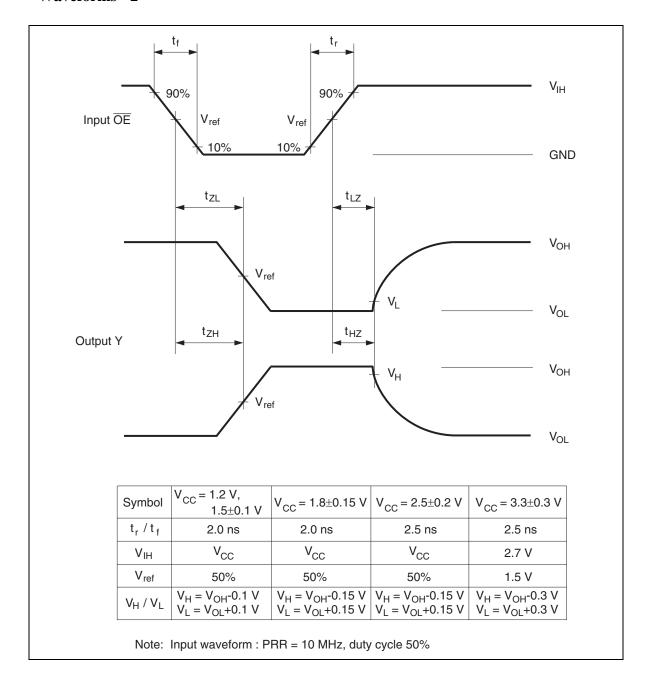
### Waveforms - 1



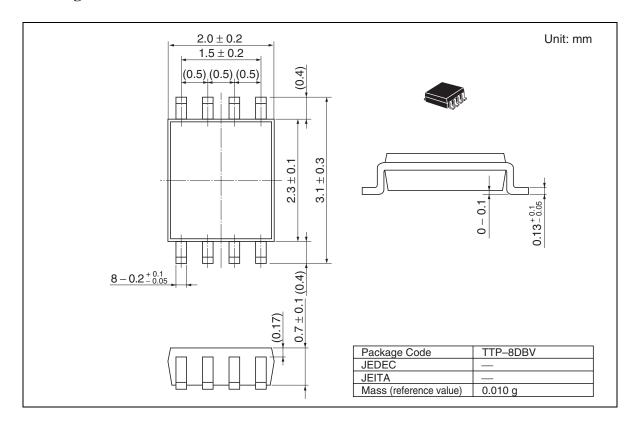
### **Test Circuit - 2**



### Waveforms - 2



### **Package Dimensions**



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